



Material Content Data Sheet



Sales Product Name				XMC4500-E144F1024 AC		Issued		24. January 2018	
MA#				MA001042918					
Package				PG-LFBGA-144-10		Weight*		367.72 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	12.464	3.39	3.39	33897	33897	
wire	noble metal	palladium	7440-05-3	0.007	0.00		18		
	non noble metal	copper	7440-50-8	0.664	0.18	0.18	1805	1823	
encapsulation	organic material	carbon black	1333-86-4	0.376	0.10		1021		
	plastics	epoxy resin	-	25.910	7.05		70463		
	inorganic material	silicondioxide	60676-86-0	161.471	43.92	51.07	439120	510604	
substrate	inorganic material	Metal Hydroxide	-	2.532	0.69		6885		
	inorganic material	bariumsulfate	7727-43-7	3.918	1.07		10656		
	plastics	acrylic resin	-	4.535	1.23		12332		
	inorganic material	silicondioxide	60676-86-0	8.017	2.18		21802		
	plastics	epoxy resin	-	16.478	4.48		44811		
	inorganic material	glass fibre	-	17.722	4.82		48194		
	non noble metal	copper	7440-50-8	60.691	16.50	30.97	165050	309730	
plating	noble metal	gold	7440-57-5	0.198	0.05		538		
	non noble metal	nickel	7440-02-0	0.541	0.15	0.20	1472	2010	
solderball	noble metal	silver	7440-22-4	1.744	0.47		4742		
	non noble metal	tin	7440-31-5	48.079	13.08	13.55	130750	135492	
glue	plastics	epoxy resin	-	0.592	0.16		1611		
	noble metal	silver	7440-22-4	1.777	0.48	0.64	4833	6444	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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